

MOSFETs Silicon N-Channel MOS (DTMOS V)

# **TK290P60Y**

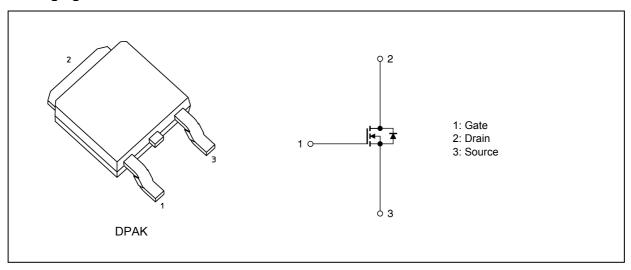
#### 1. Applications

· Switching Voltage Regulators

#### 2. Features

- (1) Low drain-source on-resistance:  $R_{DS(ON)} = 0.23 \Omega$  (typ.) by using Super Junction Structure: DTMOS
- (2) Easy to control Gate switching
- (3) Enhancement mode:  $V_{th} = 3 \text{ to } 4 \text{ V } (V_{DS} = 10 \text{ V}, I_D = 0.45 \text{ mA})$

#### 3. Packaging and Internal Circuit



## 4. Absolute Maximum Ratings (Note) (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteris	Symbol	Rating	Unit		
Drain-source voltage			V <sub>DSS</sub>	600	V
Gate-source voltage			V <sub>GSS</sub>	±30	]
Drain current (DC)	(T <sub>c</sub> = 25 °C)	(Note 1)	I <sub>D</sub>	11.5	Α
Drain current (DC)	(T <sub>c</sub> = 100 °C)	(Note 1)	I <sub>D</sub>	7.3	Α
Drain current (pulsed)	(T <sub>c</sub> = 25 °C)	(Note 1)	I <sub>DP</sub>	46	Α
Power dissipation	(T <sub>c</sub> = 25 °C)		P <sub>D</sub>	100	W
Single-pulse avalanche energy		(Note 2)	E <sub>AS</sub>	114	mJ
Single-pulse avalanche current			I <sub>AS</sub>	3	Α
Reverse drain current (DC)		(Note 1)	I <sub>DR</sub>	11.5	]
Reverse drain current (pulsed)		(Note 1)	I <sub>DRP</sub>	46	Α
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production



#### 5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance	R <sub>th(ch-c)</sub>	1.25	°C/W
Channel-to-ambient thermal resistance	R <sub>th(ch-a)</sub>	125	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25 °C (initial), L = 22.3 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AS}$  = 3 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μΑ
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	_	_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	V
Gate threshold voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.45 mA	3	_	4	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.8 A	_	0.23	0.29	Ω

## 6.2. Dynamic Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	$V_{DS} = 300 \text{ V}, V_{GS} = 0 \text{ V}, f = 100 \text{ kHz}$	_	730	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	2.5	_	
Output capacitance	C <sub>oss</sub>		_	26	_	
Effective output capacitance	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 to 400 V, V <sub>GS</sub> = 0 V	_	48	_	
Gate resistance	r <sub>g</sub>	V <sub>DS</sub> = OPEN , f = 1 MHz	_	32	_	Ω
Switching time (rise time)	t <sub>r</sub>	See Figure 6.2.1	_	25	_	ns
Switching time (turn-on time)	t <sub>on</sub>		_	65	_	
Switching time (fall time)	t <sub>f</sub>		_	8.5	_	
Switching time (turn-off time)	t <sub>off</sub>		_	170	_	
MOSFET dv/dt ruggedness	dv/dt	$V_{DS} \le V_{(BR)DSS}$ , $I_D \le 5.8 A$	50	_		V/ns

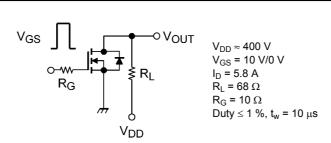


Fig. 6.2.1 Switching Time Test Circuit

## 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	$Q_g$	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 11.5 \text{ A}$		25		nC
Gate-source charge 1	Q <sub>gs1</sub>			4	_	
Gate-drain charge	$Q_{gd}$			13		

# 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	$V_{DSF}$	I <sub>DR</sub> = 11.5 A, V <sub>GS</sub> = 0 V	_		-1.7	V
Reverse recovery time	t <sub>rr</sub>	V <sub>DD</sub> ≈ 400 V	_	240	_	ns
Reverse recovery charge	$Q_{rr}$	I <sub>DR</sub> = 5.8 A, V <sub>GS</sub> = 0 V   -dI <sub>DR</sub> /dt = 100 A/μs	_	2.3	_	μС
Peak reverse recovery current	I <sub>rr</sub>	-αιρκ/αι – 100 Α/μο	_	20	_	Α
Diode dv/dt ruggedness	dv/dt	$V_{DS} \le 400 \text{ V}, I_{DR} \le 5.8 \text{ A}, V_{GS} = 0 \text{ V}$	15		_	V/ns



## 7. Marking

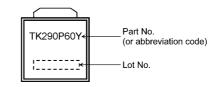


Fig. 7.1 Marking

#### 8. Characteristics Curves (Note)

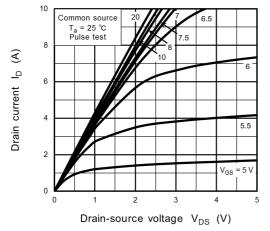
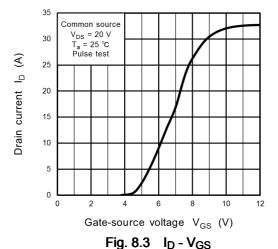
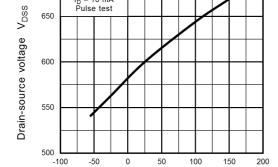


Fig. 8.1 I<sub>D</sub> - V<sub>DS</sub>





Ambient temperature  $T_a$  (°C) Fig. 8.5 V<sub>DSS</sub> - T<sub>a</sub>

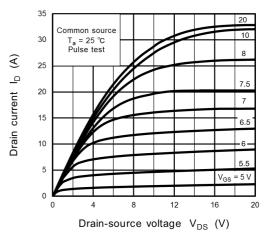


Fig. 8.2 I<sub>D</sub> - V<sub>DS</sub>

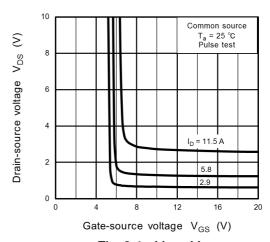


Fig. 8.4 V<sub>DS</sub> - V<sub>GS</sub>

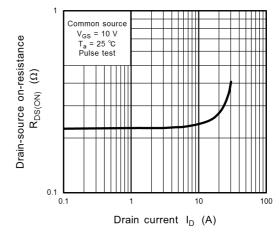


Fig. 8.6 R<sub>DS(ON)</sub> - I<sub>D</sub>

700

650

 $\leq$ 

Common source  $V_{GS} = 0 \text{ V}$   $I_D = 10 \text{ mA}$ Pulse test

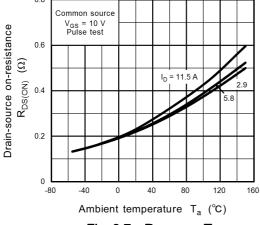
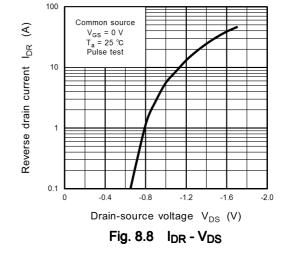


Fig. 8.7 R<sub>DS(ON)</sub> - T<sub>a</sub>



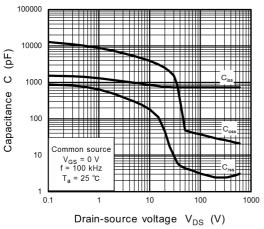


Fig. 8.9 C - V<sub>DS</sub>

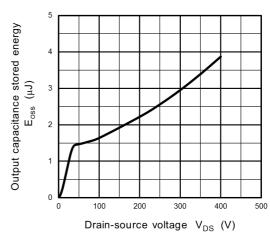


Fig. 8.10 Eoss - VDS

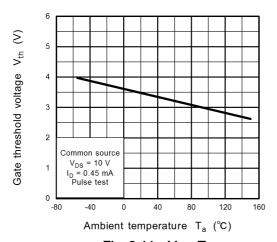


Fig. 8.11 V<sub>th</sub> - T<sub>a</sub>

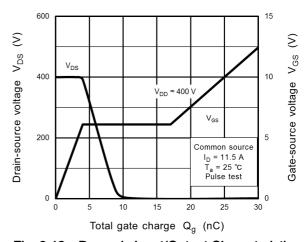


Fig. 8.12 Dynamic Input/Output Characteristics

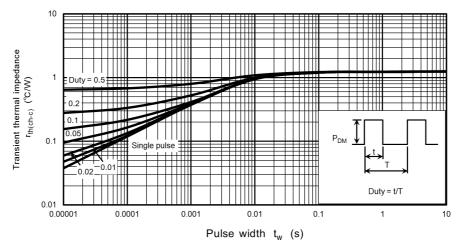


Fig. 8.13 r<sub>th</sub> - t<sub>w</sub> (Guaranteed Maximum)

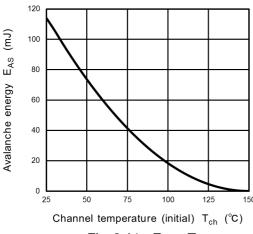


Fig. 8.14 E<sub>AS</sub> - T<sub>ch</sub> (Guaranteed Maximum)

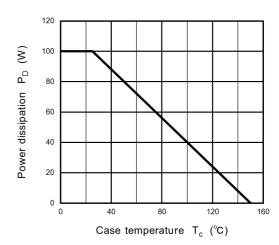
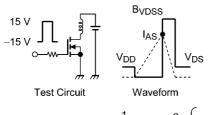


Fig. 8.15 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)



$$R_G = 25 \Omega$$
,  $V_{DD} = 90 V$   $E_{AS} = \frac{1}{2} \cdot L \cdot I_{AS}^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}}\right)$ 

Fig. 8.16 Test Circuit/Waveform

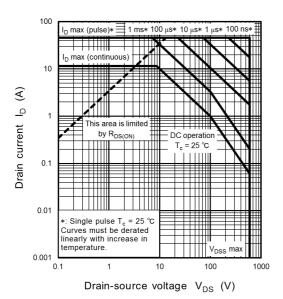


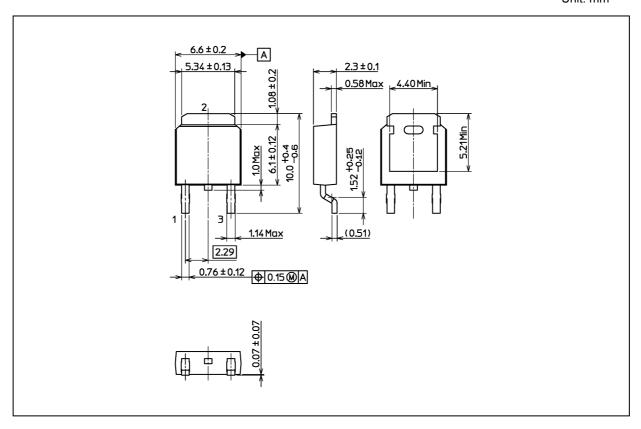
Fig. 8.17 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



## **Package Dimensions**

Unit: mm



Weight: 0.36 g (typ.)

Pack	age Name(s)
TOSHIBA: 2-7K1S	
Nickname: DPAK	



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